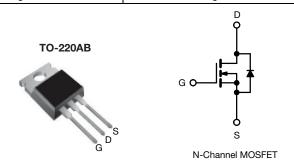


www.vishay.com

Vishay Siliconix

Power MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	1000			
R _{DS(on)} (Ω)	V _{GS} = 10 V 11			
Q _g max. (nC)	38			
Q _{gs} (nC)	4.9			
Q _{gd} (nC)	22			
Configuration	Single			



FEATURES

- Dynamic dV/dt rating
- Repetitive avalanche rated
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Note

This datasheet provides information about parts that are RoHS-compliant and / or parts that are non-RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details.

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION		
Package	TO-220AB	
Lead (Pb)-free	IRFBG20PbF	
Lead (Pb)-free	SiHFBG20-E3	
SnPb	IRFBG20	
SIIPD	SiHFBG20	

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwi			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V _{DS}	1000	,,	
Gate-Source Voltage			V_{GS}	± 20	_ V	
Continuous Drain Current	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$		1.4		
Continuous Drain Current		T _C = 100 °C	I _D	0.86	Α	
Pulsed Drain Current ^a			I _{DM}	5.6	1	
Linear Derating Factor				0.43	W/°C	
Single Pulse Avalanche Energy b			E _{AS}	200	mJ	
Repetitive Avalanche Current ^a			I _{AR}	1.4	А	
Repetitive Avalanche Energy ^a			E _{AR}	5.4	mJ	
Maximum Power Dissipation $T_C = 25 ^{\circ}C$			P _D	54	W	
Peak Diode Recovery dV/dt ^c			dV/dt	1.0	V/ns	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	- °C	
Soldering Recommendations (Peak temperature) d for 10 s				300		
Mounting Toyaus	6-32 or M3 screw			10	lbf ⋅ in	
Mounting Torque				1.1	N⋅m	

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11). b. $V_{DD}=50$ V, starting $T_J=25$ °C, L=193 $\mu H,$ $R_g=25$ $\Omega,$ $I_{AS}=1.4$ A (see fig. 12). c. $I_{SD}\leq 1.4$ A, $dI/dt\leq 60$ A/ $\mu s,$ $V_{DD}\leq 600,$ $T_J\leq 150$ °C. d. 1.6 mm from case.



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	62		
Case-to-Sink, Flat, Greased Surface	R _{thCS}	0.50	=	°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	-	2.3		

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static		<u> </u>			I.	•	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	= 0 V, I _D = 250 μA	1000	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = 1 mA		-	1.2	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
Gate-Source Leakage	I _{GSS}		V _{GS} = ± 20 V	-	-	± 100	nA
Zero Gate Voltage Drain Current		V _{DS} =	1000 V, V _{GS} = 0 V	-	-	100	^
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 800 V, V _{GS} = 0 V, T _J = 125 °C		1	-	500	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 0.84 A ^b	-	-	11	Ω
Forward Transconductance	9 _{fs}	V _{DS} =	$50 \text{ V}, I_D = 0.84 \text{ A}^{\text{ b}}$	1.0	-	-	S
Dynamic							
Input Capacitance	C_{iss}	$V_{GS} = 0 V$,		1	500	-	pF
Output Capacitance	C_{oss}]	$V_{DS} = 25 V$,		52	-	
Reverse Transfer Capacitance	C_{rss}	f = 1	.0 MHz, see fig. 5	1	17	-	
Total Gate Charge	Q_g			-	-	38	
Gate-Source Charge	Q_{gs}	V _{GS} = 10 V	$I_D = 1.4 \text{ A}, V_{DS} = 400 \text{ V},$ see fig. 6 and 13 b	-	-	4.9	nC
Gate-Drain Charge	Q _{gd}		3	-	-	22	1
Turn-On Delay Time	t _{d(on)}			-	9.4	-	
Rise Time	t _r	V _{DD} =	: 500 V, I _D = 1.4 A,	-	17	-	
Turn-Off Delay Time	t _{d(off)}		$R_D = 370 \Omega$, see fig. 10 b	-	58	-	ns
Fall Time	t _f			-	31	-	1
Internal Drain Inductance	L_{D}	Between lead, 6 mm (0.25") from		-	4.5	-	
Internal Source Inductance	L _S	package and die contact	center of	-	7.5	-	nH
Gate Input Resistance	R _g	f = 1	MHz, open drain	0.6	-	3.4	Ω
Drain-Source Body Diode Characteristic	s						•
Continuous Source-Drain Diode Current	Is	showing the integral reverse		1.4	A		
Pulsed Diode Forward Current ^a	I _{SM}			-	5.6		
Body Diode Voltage	V _{SD}	T _J = 25 °C	, I _S = 1.4 A, V _{GS} = 0 V ^b	-	-	1.5	V
Body Diode Reverse Recovery Time	t _{rr}	- 130 190		190	ns		
Body Diode Reverse Recovery Charge	Q _{rr}	$J = 25 \text{C}, I_{\text{F}}$	= 1.4 A, dl/dt = 100 A/µs b	-	0.46	0.69	μC
Forward Turn-On Time	t _{on}	Intrinsic tu	ırn-on time is negligible (turn	on is dor	ninated b	y L _S and	L _D)

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width $\leq 300~\mu s$; duty cycle $\leq 2~\%$.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

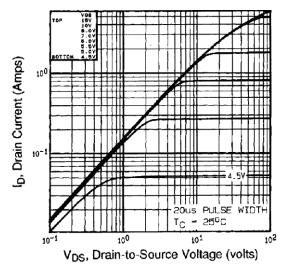


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

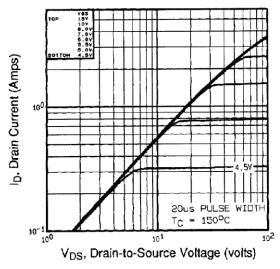


Fig. 2 - Typical Output Characteristics, $T_C = 150$ °C

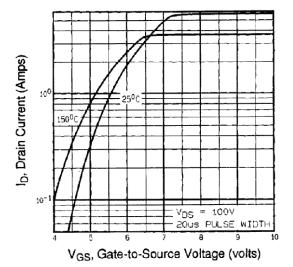


Fig. 3 - Typical Transfer Characteristics

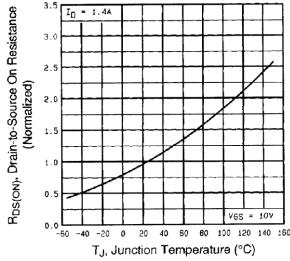


Fig. 4 - Normalized On-Resistance vs. Temperature



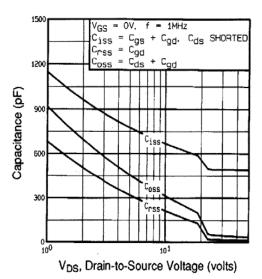


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

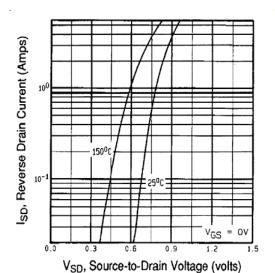


Fig. 7 - Typical Source-Drain Diode Forward Voltage

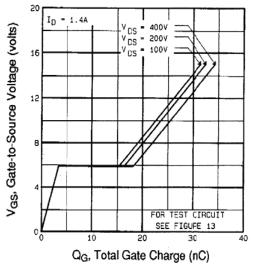


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

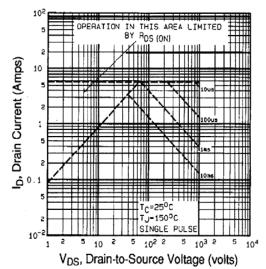


Fig. 8 - Maximum Safe Operating Area



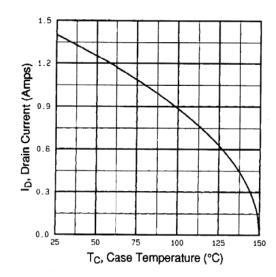


Fig. 9 - Maximum Drain Current vs. Case Temperature

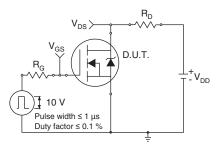


Fig. 10a - Switching Time Test Circuit

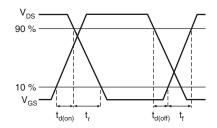


Fig. 10b - Switching Time Waveforms

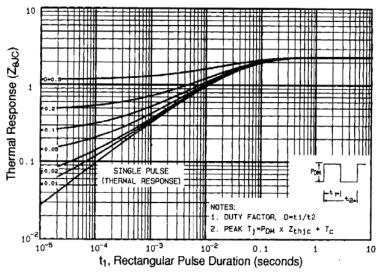


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

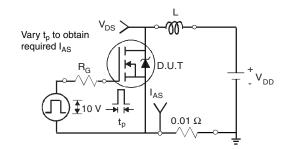


Fig. 12a - Unclamped Inductive Test Circuit

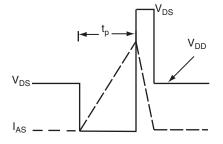


Fig. 12b - Unclamped Inductive Waveforms



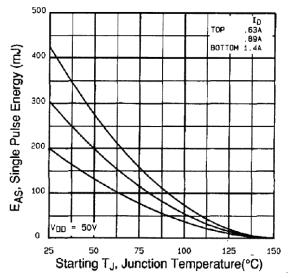


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

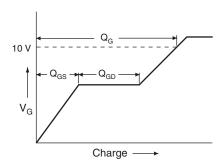


Fig. 13a - Basic Gate Charge Waveform

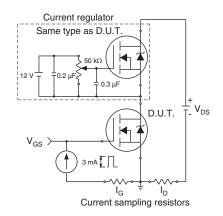
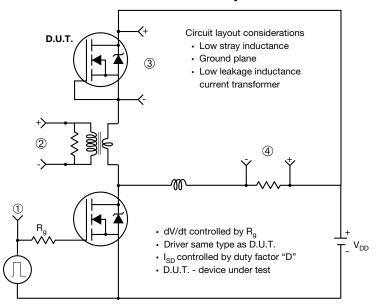


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



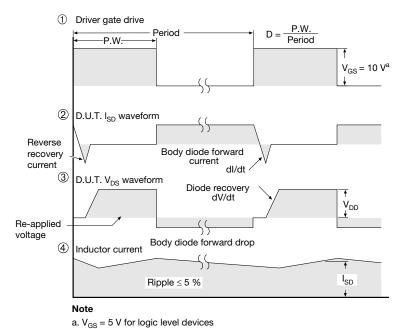


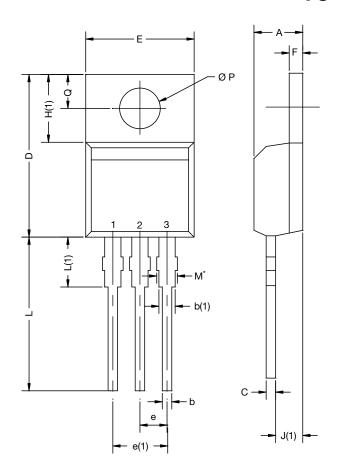
Fig. 14 - For N-Channel

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TO-220-1



DIM.	MILLIN	METERS	INCHES		
	MIN.	MAX.	MIN.	MAX.	
Α	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
Е	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØР	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	

Note

 \bullet $M^{\star}=0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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